# International Rectifier

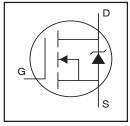
### **AUTOMOTIVE GRADE**

## AUIRFR2405

### HEXFET® Power MOSFET

#### **Features**

- Advanced Planar Technology
- Dynamic dV/dT Rating
- Low On-Resistance
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Repetitive Avalanche Allowed up to Tjmax
- Lead-Free, RoHS Compliant
- Automotive Qualified\*



$V_{(BR)DSS}$	55V
R <sub>DS(on)</sub> typ.	11.8m $\Omega$
max	16m $\Omega$
I <sub>D (Silicon Limited)</sub>	56A ⑥
I <sub>D (Package Limited)</sub>	30A

### **Description**

Specifically designed for Automotive applications, this Stripe Planar design of HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low on-resistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.



G	D	S
Gate	Drain	Source

### **Absolute Maximum Ratings**

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature  $(T_A)$  is  $25^{\circ}C$ , unless otherwise specified.

	Parameter	Max.	Units
I <sub>D</sub> @ T <sub>C</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V (Silicon Limited)	56©	
I <sub>D</sub> @ T <sub>C</sub> = 100°C	Continuous Drain Current, VGS @ 10V (Silicon Limited)	40®	Α
I <sub>D</sub> @ T <sub>C</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V (Package Limited)	30	
I <sub>DM</sub>	Pulsed Drain Current ①	220	
P <sub>D</sub> @T <sub>C</sub> = 25°C	Power Dissipation	110	W
	Linear Derating Factor	0.71	W/°C
$V_{GS}$	Gate-to-Source Voltage	± 20	٧
E <sub>AS</sub>	Single Pulse Avalanche Energy (Thermally Limited) <sup>②</sup>	130	mJ
I <sub>AR</sub>	Avalanche Current ①	34	Α
E <sub>AR</sub>	Repetitive Avalanche Energy ①	11	mJ
dv/dt	Peak Diode Recovery dv/dt ③	5.0	V/ns
$T_J$	Operating Junction and	-55 to + 175	
T <sub>STG</sub>	Storage Temperature Range		°C
	Soldering Temperature, for 10 seconds (1.6mm from case)	300	

### **Thermal Resistance**

	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Junction-to-Case ®		1.4	
$R_{\theta JA}$	Junction-to-Ambient (PCB Mount) <sup>⑦</sup>		50	°C/W
$R_{\theta JA}$	Junction-to-Ambient		110	

HEXFET® is a registered trademark of International Rectifier.

<sup>\*</sup>Qualification standards can be found at http://www.irf.com/

### Static Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	55			V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient		0.052		V/°C	Reference to 25°C, I <sub>D</sub> = 1mA
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance		11.8	16	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 34A ④
V <sub>GS(th)</sub>	Gate Threshold Voltage	2.0		4.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$
gfs	Forward Transconductance	30			S	$V_{DS} = 25V, I_D = 34A^{\textcircled{4}}$
I <sub>DSS</sub>	Drain-to-Source Leakage Current			20	μΑ	$V_{DS} = 55V, V_{GS} = 0V$
				250		$V_{DS} = 44V, V_{GS} = 0V, T_{J} = 150^{\circ}C$
I <sub>GSS</sub>	Gate-to-Source Forward Leakage			200	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage			-200		$V_{GS} = -20V$

### Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
$Q_g$	Total Gate Charge		70	110		$I_D = 34A$
Q <sub>gs</sub>	Gate-to-Source Charge		16	23	nC	$V_{DS} = 44V$
$Q_{gd}$	Gate-to-Drain ("Miller") Charge		19	29	1	V <sub>GS</sub> = 10V ④
t <sub>d(on)</sub>	Turn-On Delay Time		15			$V_{DD} = 28V$
t <sub>r</sub>	Rise Time		130		1	$I_D = 34A$
t <sub>d(off)</sub>	Turn-Off Delay Time		55		ns	$R_G = 6.8\Omega$
t <sub>f</sub>	Fall Time		78		1	$R_D = 10\Omega \ \oplus$
L <sub>D</sub>	Internal Drain Inductance		4.5			Between lead,
					nΗ	6mm (0.25in.)
L <sub>S</sub>	Internal Source Inductance		7.5			from package
						and center of die contact
C <sub>iss</sub>	Input Capacitance		2430			$V_{GS} = 0V$
Coss	Output Capacitance		470		рF	$V_{DS} = 25V$
C <sub>rss</sub>	Reverse Transfer Capacitance		100			f = 1.0MHz, See Fig. 5
Coss	Output Capacitance		2040			$V_{GS} = 0V, V_{DS} = 1.0V, f = 1.0MHz$
Coss	Output Capacitance		350		1	$V_{GS} = 0V, V_{DS} = 44V, f = 1.0MHz$
C <sub>oss</sub> eff.	Effective Output Capacitance (9)	<b>—</b>	350		1	$V_{GS} = 0V$ , $V_{DS} = 0V$ to 44V
		_				

### **Diode Characteristics**

	Parameter	Min.	Тур.	Max.	Units	Conditions
I <sub>S</sub>	Continuous Source Current			56®		MOSFET symbol
	(Body Diode)				Α	showing the
I <sub>SM</sub>	Pulsed Source Current			220		integral reverse
	(Body Diode) ①					p-n junction diode.
$V_{SD}$	Diode Forward Voltage			1.3	V	$T_J = 25^{\circ}C$ , $I_S = 34A$ , $V_{GS} = 0V$ ④
t <sub>rr</sub>	Reverse Recovery Time		62	93	ns	$T_J = 25^{\circ}C, I_F = 34A$
Q <sub>rr</sub>	Reverse Recovery Charge	l	170	260	nC	di/dt = 100A/µs ④
t <sub>on</sub>	Forward Turn-On Time	Intrinsi	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)			

### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- $\label{eq:starting} \begin{array}{ll} \text{ Starting T}_J = 25^{\circ}\text{C}, \ L = 0.22\text{mH} \\ \text{R}_G = 25\Omega, \ \text{I}_{AS} = 34\text{A}. \end{array}$
- $\label{eq:loss} \begin{array}{l} \text{ } 3 \text{ } I_{SD} \leq 34A, \text{ di/dt} \leq 190A/\mu s, \text{ } V_{DD} \leq V_{(BR)DSS}, \\ T_{J} \leq 175^{\circ}C. \end{array}$
- 4 Pulse width  $\leq 300 \mu s$ ; duty cycle  $\leq 2\%$ .
- $\ ^{\circ}$  C  $_{\circ SS}$  eff. is a fixed capacitance that gives the same charging time as C  $_{\circ SS}$  while V  $_{DS}$  is rising from 0 to 80% V  $_{DSS}.$
- © Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 30A.
- When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.
- $\otimes$  R<sub> $\theta$ </sub> is measured at T<sub>J</sub> of approximately 90°C.

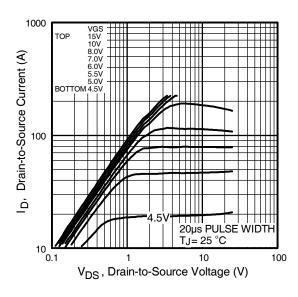
### Qualification Information<sup>†</sup>

		Automotive			
		(per AEC-Q101) <sup>††</sup>			
Qualification	n Level	Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.			
Moisture Ser	Moisture Sensitivity Level D-Pak MSL1		MSL1		
	Machine Model	Class M4 (+/- 500V) <sup>†††</sup>			
		AEC-Q101-002			
ESD	Human Body Model	Class H1C (+/- 2000V) <sup>†††</sup>			
ESD			AEC-Q101-001		
	Charged Device	Class C5 (+/- 2000V) <sup>†††</sup>			
	Model	AEC-Q101-005			
RoHS Comp	liant	Yes			

<sup>†</sup> Qualification standards can be found at International Rectifier's web site: http://www.irf.com/

<sup>††</sup> Exceptions (if any) to AEC-Q101 requirements are noted in the qualification report.

<sup>†††</sup> Highest passing voltage.



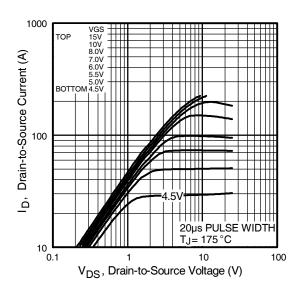
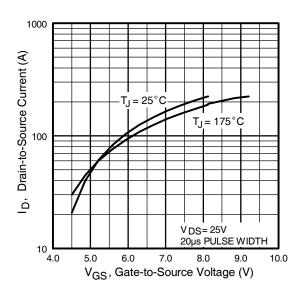


Fig 1. Typical Output Characteristics

Fig 2. Typical Output Characteristics



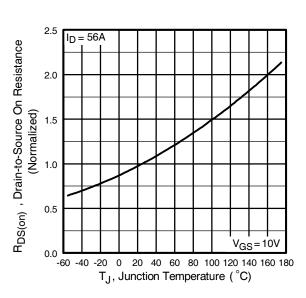
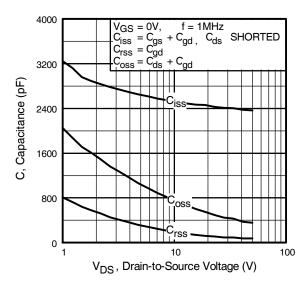
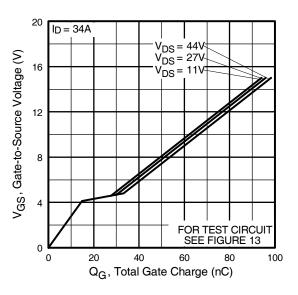


Fig 3. Typical Transfer Characteristics

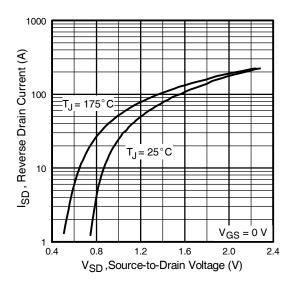
**Fig 4.** Normalized On-Resistance Vs. Temperature

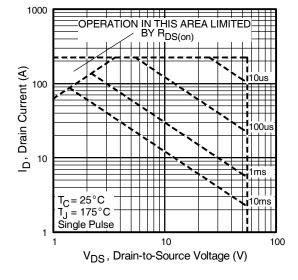




**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage

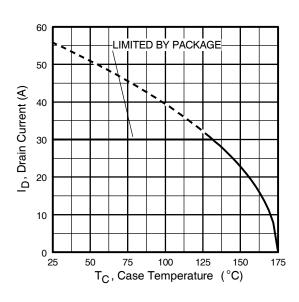
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage





**Fig 7.** Typical Source-Drain Diode Forward Voltage

Fig 8. Maximum Safe Operating Area



**Fig 9.** Maximum Drain Current Vs. Case Temperature

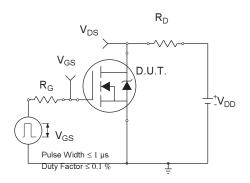


Fig 10a. Switching Time Test Circuit

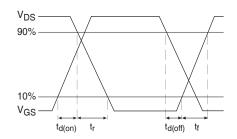


Fig 10b. Switching Time Waveforms

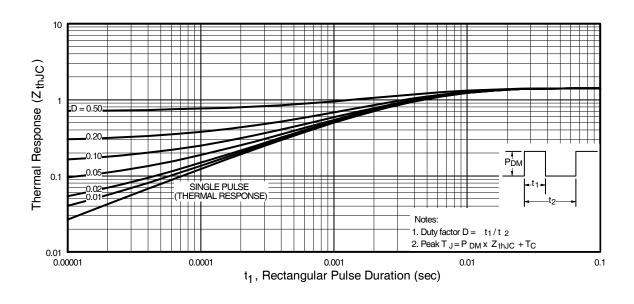


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

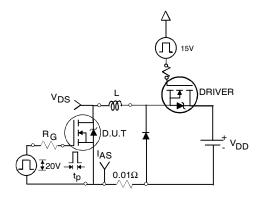


Fig 12a. Unclamped Inductive Test Circuit

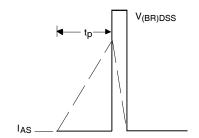
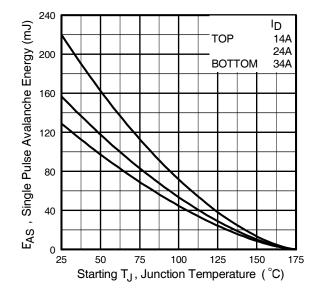


Fig 12b. Unclamped Inductive Waveforms



**Fig 12c.** Maximum Avalanche Energy Vs. Drain Current

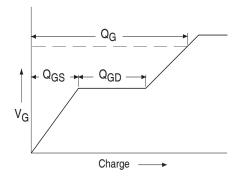


Fig 13a. Basic Gate Charge Waveform

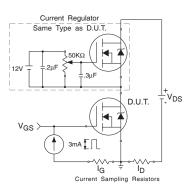
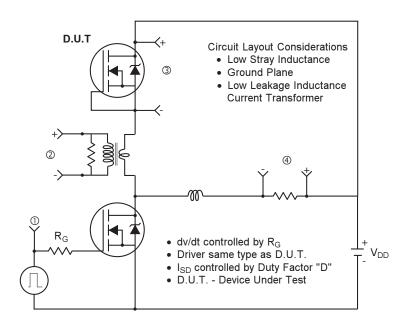


Fig 13b. Gate Charge Test Circuit

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### Peak Diode Recovery dv/dt Test Circuit



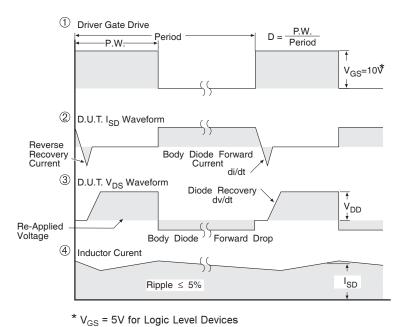
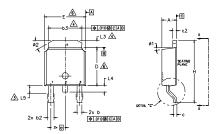
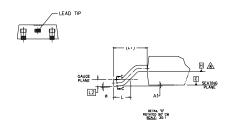


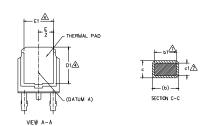
Fig 14. For N-Channel HEXFET® Power MOSFETs

### D-Pak (TO-252AA) Package Outline

Dimensions are shown in millimeters (inches)







- 1.- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
  2.- DIMENSION ARE SHOWN IN INCHES [MILLIMETERS]
- A- LEAD DIMENSION UNCONTROLLED IN L5.
- A- DIMENSION D1, E1, L3 & b3 ESTABLISH A MINIMUM MOUNTING SURFACE FOR THERMAL PAD.
- AND DIMENSION DT, ET, L3 & B5 ESTABLISH A MINIMUM MOUNTING SUPFACE FOR THERMAL PAD.

  SECTION OF THE LEAD BETWEEN .005 AND 0.10
  [0.13 AND 0.25] FROM THE LEAD TIP.

  AND DIMENSION D & E DO NOT INCLUDE MOLD FLASH, MOLD FLASH SHALL NOT EXCEED .005 [0.13] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.

  DIMENSION b1 & c1 APPLIED TO BASE METAL ONLY.
- A- DATUM A & B TO BE DETERMINED AT DATUM PLANE H
- 9,- OUTLINE CONFORMS TO JEDEC OUTLINE TO-252AA.

S					
Ьů	DIMENSIONS				
B 0	MILLIM	ETERS	ERS INCHES		Ö
0	MIN.	MAX.	MIN.	MAX.	E S
A	2,18	2.39	.086	.094	
A1	-	0.13	-	.005	
ь	0.64	0.89	.025	.035	
ь1	0.65	0.79	.025	.031	7
b2	0.76	1,14	.030	.045	
ь3	4,95	5,46	.195	.215	4
С	0.46	0,61	.018	.024	
c1	0.41	0.56	.016	.022	7
c2	0.46	0.89	.018	.035	
D	5.97	6.22	.235	.245	6
D1	5.21	-	.205	-	4
Ε	6.35	6.73	.250	.265	6
E1	4,32	-	.170	-	4
e	2.29	BSC	.090	BSC	
н	9.40	10.41	.370	.410	
L	1.40	1.78	.055	.070	
L1		BSC	.108		
L2	0.51	BSC	.020	BSC	
L3	0.89	1.27	.035	.050	4
L4	-	1.02	-	.040	
L5	1,14	1.52	.045	.060	3
ø	0.	10"	0.	10*	
ø1	0,	15*	0,	15*	
ø2	25*	35*	25*	35°	

#### LEAD ASSIGNMENTS

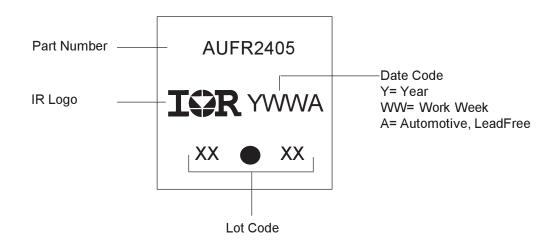
#### HEXFET

- 1.- GATE 2.- DRAIN
- 3.- SOURCE 4.- DRAIN

#### IGBT & CoPAK

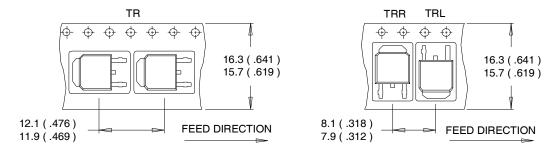
- 1.- GATE 2.- COLLECTOR 3.- EMITTER 4.- COLLECTOR

### D-Pak Part Marking Information



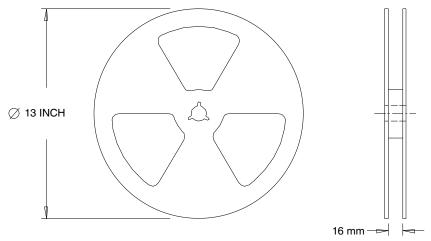
### D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



#### NOTES:

- 1. CONTROLLING DIMENSION : MILLIMETER.
- 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
- 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



### NOTES:

1. OUTLINE CONFORMS TO EIA-481.

### Ordering Information

Base part number	Package Type	Standard Pack		Complete Part Number
		Form	Quantity	
AUIRFR2405	Dpak	Tube	75	AUIRFR2405
		Tape and Reel	2000	AUIRFR2405TR
		Tape and Reel Left	3000	AUIRFR2405TRL
		Tape and Reel Right	3000	AUIRFR2405TRR

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